# SH260 High Performance, Polyimide Laminate and Prepreg

Shengyi Technology Rigid Laminate Systems offers a product line of polyimide-based copper clad laminates and prepreg for high temperature required PCB applications. These products utilize modified polyimide, fully cured without the use of MDA, and can provide high thermal performance without the difficulties of brittleness. The attracting cost-performance makes it available in commercial and industrial electronic applications.

## FEATURES

- Polyimide system provides ultra-high thermal performance, with Tg > 250℃ (TMA), Td >405℃ (5% loss, TGA), and T300>60min.
- Lower Z-axis CTE of 1.20% ( 50-260℃) offering superior PTH reliability.
- Maintain mechanical strength and bonding strength at high temperature.
- Tough resin system, Non-MDA chemistry.
- Halogen-free chemistry compatible with lead-free processing. RoHS/WEEE compliant.
- IPC 4101C/40, /41

## APPLICATIONS

- Aerospace
- Burn-in Boards
- Down Hole
- Backplanes
- Under-hood automotive controls

## PURCHASING INFORMATION

### Laminate

| Thickness | Copper foil | Standard Size |
|---|---|---|
| 0.05mm (.002”)<br>~<br>2.36mm (.093”) | 12μm<br>~<br>105μm | 915×1220mm(36”×48”)<br>1020×1220mm(40”×48”)<br>1070×1220mm(42”×48”) |

### Prepreg

| Glass Type | RC % | Tolerance |
|---|---|---|
| 106 | 72 | +/-3% |
| 1080 | 63 | |
| 2313 | 55 | |
| 2116 | 50 | |
| 7628 | 40 | |

*Other sheet and panel size could be available upon request.

All test data provides are typical values and not intended to be specification values. Shengyi Sci. Tech reserves the right to make changes without further notice to the product herein to improve reliability, function or design.